

SPECIFICATIONS:

- ELECTRICAL:**
- RATED CURRENT: 5A
 - RATED VOLTAGE: 300VDC
 - WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 MIN
 - INSULATION RESISTANCE: > 1,000 mΩ at 500VDC
 - CONTACT RESISTANCE: 13mOhms MAX
 - DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN
 - OPERATING TEMPERATURE: -55°C TO +105°C

- MATERIALS:**
- SHELL: NICKEL PLATED STEEL
 - BRACKET: NICKEL PLATED STEEL
 - INSULATOR: NYLON 6T, UL 94V-0, BLACK
 - PROCESS TEMP: 260°C
 - INSULATOR: PATONE #322C, COLOR=Pc99
 - CONTACT: TIN PLATED PHOSPHOR BRONZE
GOLD FLASH MATING AREA
TIN PLATED SOLDER AREA

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

RoHS COMPLIANT

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



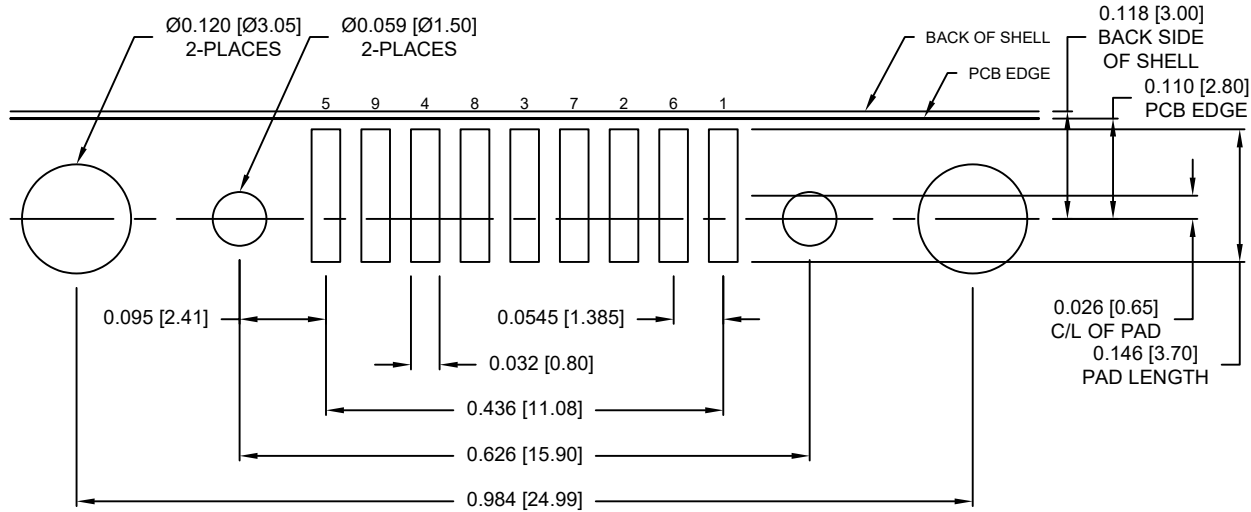
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.

DRAWN:
C. SMITH

DATE:
04/14/2009

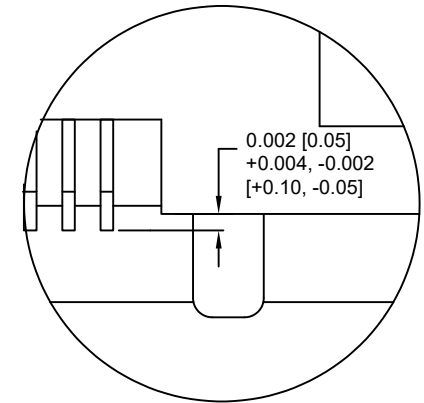
NorComp

SCALE: NTS	SHEET 1	OF 2	REV 14
DWG NO. 190-009-163R001			



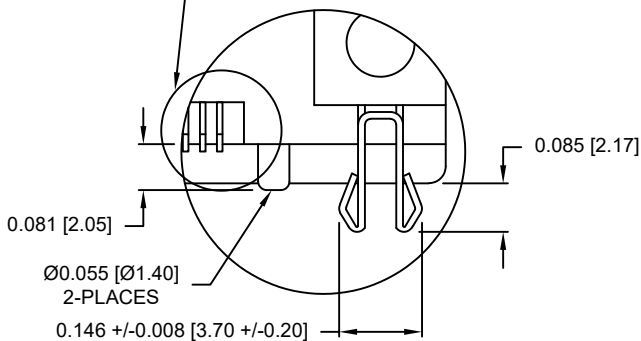
RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT
5 9 4 8 3 7 2 6 1

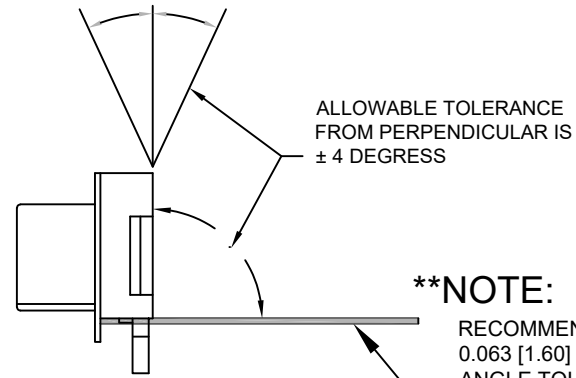


DETAIL "B"
CONTACT COPLANARITY

SEE DETAIL "B"
FOR CONTACT
COPLANARITY



DETAIL "A"



****NOTE:**

RECOMMENDED PCB THICKNESS IS
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN
ANGLE TOLERANCE

RoHS COMPLIANT

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.

DRAWN:

C. SMITH

DATE:

04/14/2009

NorComp

SCALE:

NTS

SHEET

OF

2

2

REV

14

DWG NO.

190-009-163R001